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(DE)(57) **ABSTRACT**(21) Appl. No.: **17/763,377**(22) PCT Filed: **Aug. 21, 2020**(86) PCT No.: **PCT/EP2020/073471**

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A support for at least one electrical component includes a heat sink having a heat sink surface and two opposing lateral walls protruding from the heat sink surface. The heat sink includes a base body made of aluminum and a copper layer as a heat spreading layer which forms the heat sink surface. The copper layer is produced together with the base body through continuous casting, or with the copper layer being applied additively through cold gas spraying to a surface of the base body. Two spaced-apart sealing blocks lie on the heat sink surface, with each of the two sealing blocks extending between the two lateral walls and contacting the two lateral walls. A support structure is arranged on the heat sink surface between the two sealing blocks.

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